

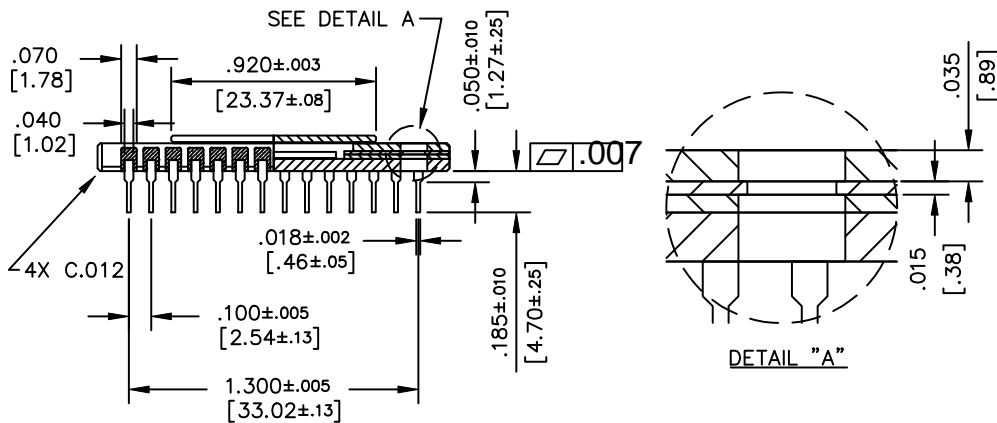
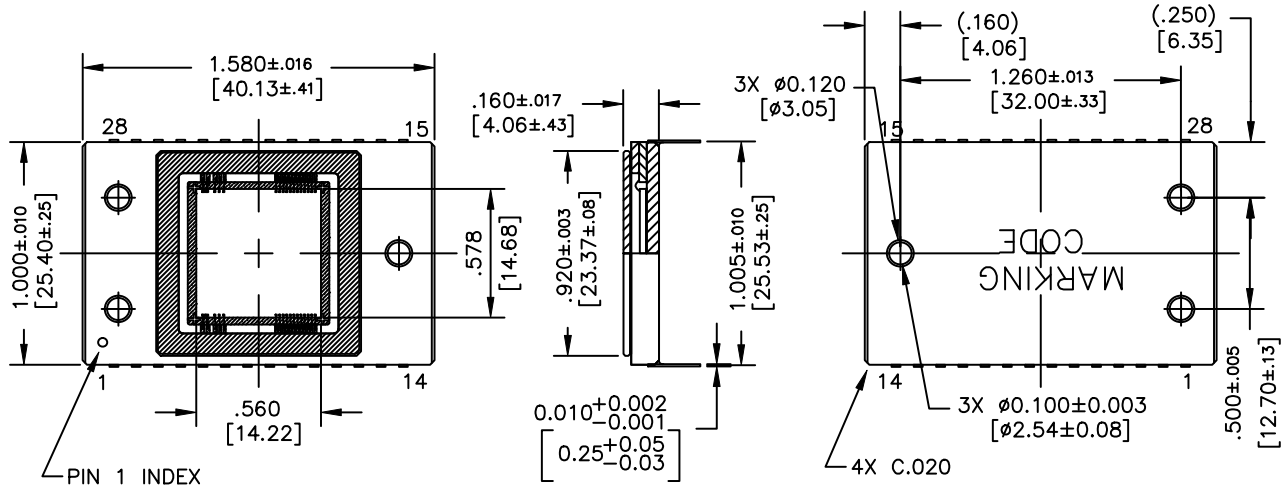
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®



CERAMIC DIP 28, 40.13x18.29, 2.54P
CASE 125BB
ISSUE O

DATE 30 JUN 2014



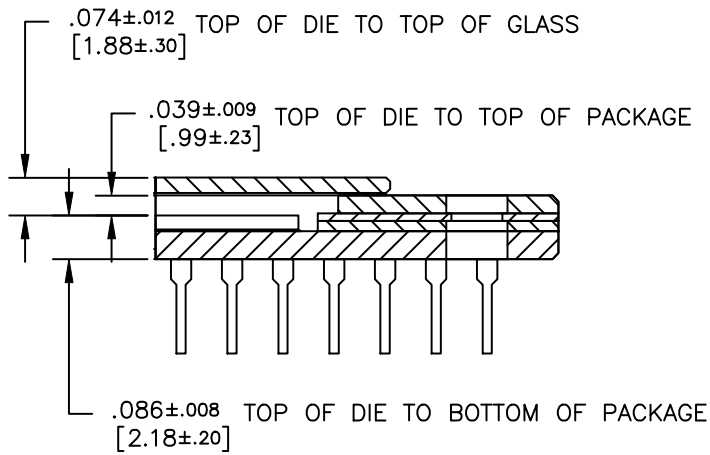
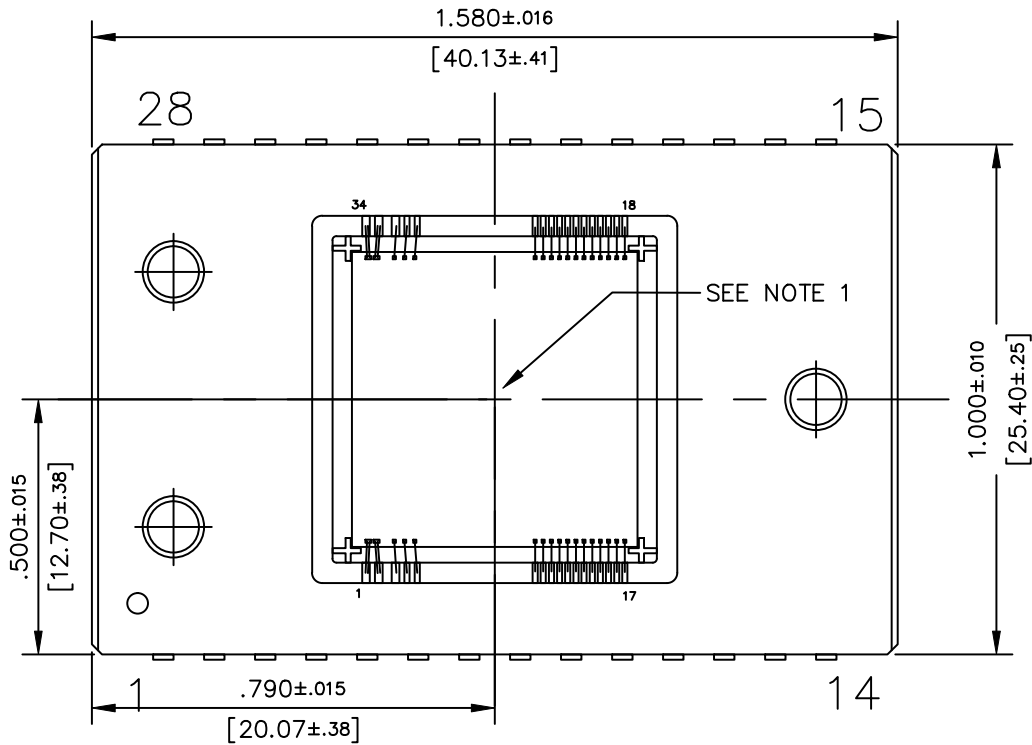
NOTES:
 1. COVER GLASS IS MANUALLY PLACED AND VISUALLY ALIGNED OVER DIE – LOCATION ACCURACY IS NOT GUARANTEED.

Dimensions in: Inches [mm]

DOCUMENT NUMBER:	98AON87221F	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
REFERENCE:		
DESCRIPTION:	CERAMIC DIP 28, 40.13x18.29, 2.54P	PAGE 1 OF 3

CERAMIC DIP 28, 40.13x18.29, 2.54P
CASE 125BB
ISSUE O

DATE 30 JUN 2014



- NOTES:
1. CENTER OF IMAGE AREA IS OFFSET FROM CENTER OF PACKAGE BY (0.00,0.00)MM NOMINAL.
 2. DIE IS ALIGNED WITHIN +/− 2 DEGREE OF ANY PACKAGE CAVITY EDGE.

Dimensions in: Inches [mm]

DOCUMENT NUMBER:	98AON87221F	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
REFERENCE:		
DESCRIPTION:	CERAMIC DIP 28, 40.13x18.29, 2.54P	PAGE 2 OF 3

